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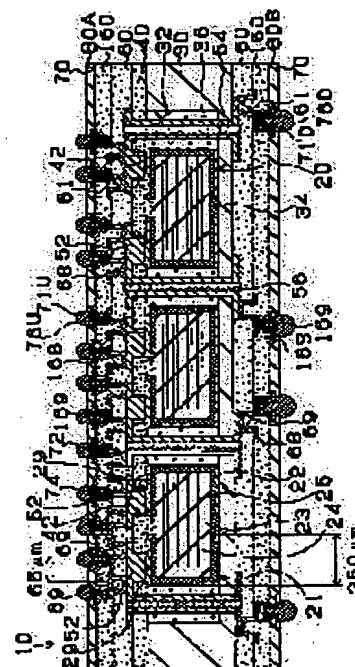
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## (54) PRINTED WIRING BOARD AND MANUFACTURING METHOD THEREOF

(57)Abstract:

**PROBLEM TO BE SOLVED:** To provide a printed wiring board together with its manufacturing method which incorporates capacitors for raised connection reliability.  
**SOLUTION:** A core substrate 30 incorporates chip capacitors 20, and relatively large vias 52 which connect terminals 21 and 22 of the chip capacitors 20 is formed on the chip capacitors 20. A plurality of relatively small vias 69 connected to the vias 52 are arranged at an inner-layer resin insulating layer 60 on the upper surface of the core substrate 30. Thus, the terminals 21 and 22 of the capacitors 20 are surely connected to the vias 52 by coping with displacement of the capacitors 20.



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